# Silicon P-Channel MOS FET

# HITACHI

ADE-208-382 1st. Edition

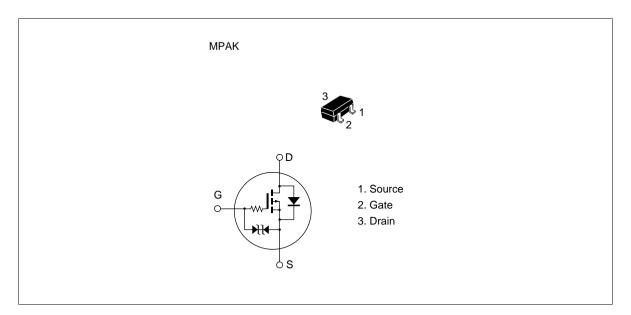
#### Application

Low frequency power switching

#### Features

- Low on-resistance.
- Low drive power
- 2.5 V gate drive device.
- Small package (MPAK).

#### Outline





# **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

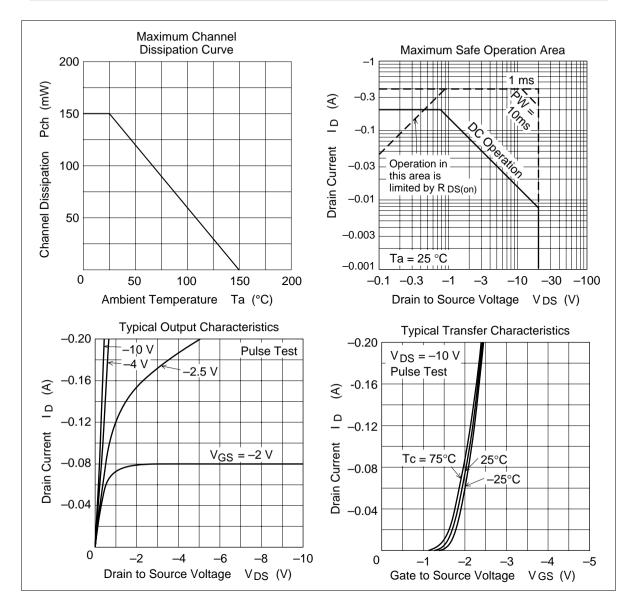
Item	Symbol	Ratings	Unit	
Drain to source voltage	V <sub>DSS</sub>	-20	V	
Gate to source voltage	V <sub>GSS</sub>	±20	V	
Drain current	I <sub>D</sub>	-0.2	А	
Drain peak current	I D(pulse) *1	-0.4	А	
Channel dissipation	Pch	150	mW	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

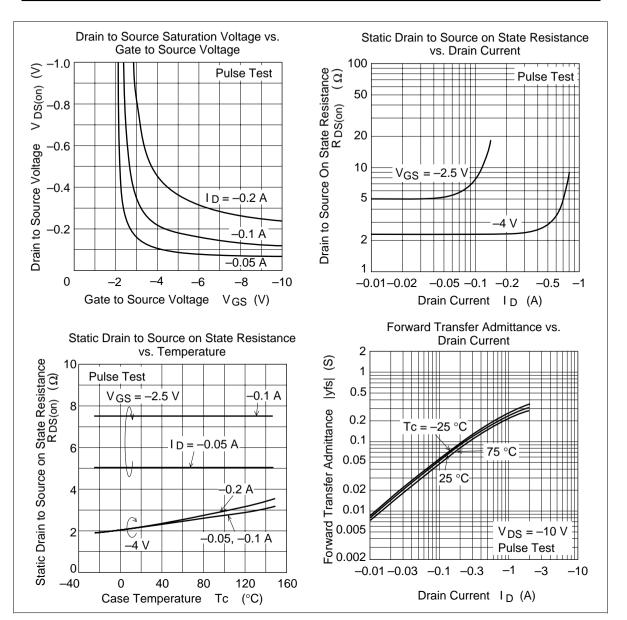
Note: 1.  $PW \le 10 \ \mu s$ , duty cycle  $\le 1\%$ Marking is "ZK–".

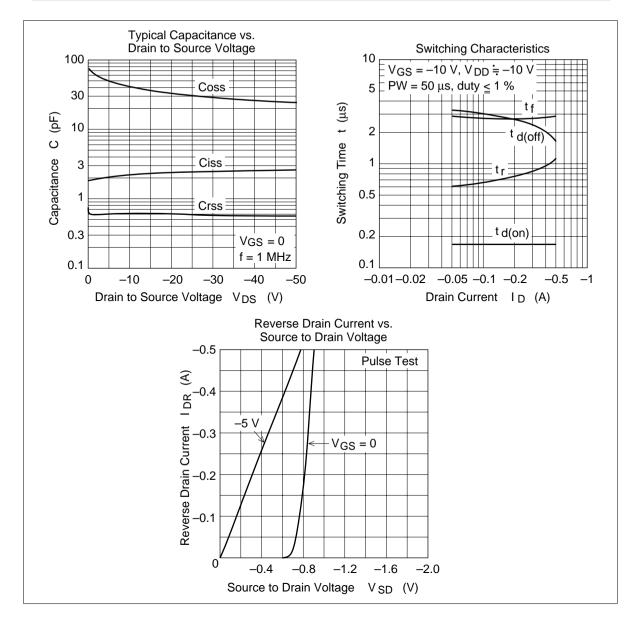
#### **Electrical Characteristics** (Ta = 25°C)

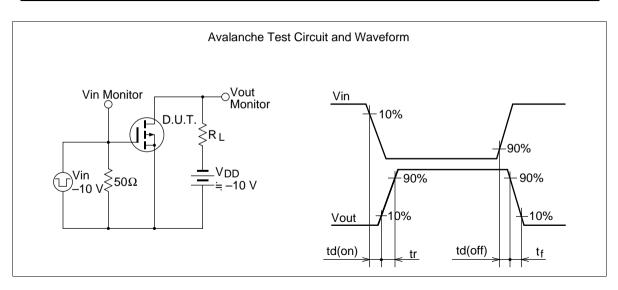
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	-20	_	_	V	$I_{\rm D} = -100 \ \mu A, \ V_{\rm GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	-1.0	μΑ	$V_{\rm DS} = -16 \text{ V}, \text{ V}_{\rm GS} = 0$
Gate to source leak current	I <sub>GSS</sub>	—	_	±2.0	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-0.5	_	-1.5	V	$I_{\rm D} = -10 \ \mu A, \ V_{\rm DS} = -5 \ V$
Static drain to source on state resistance	$R_{\text{DS(on)}}$ 1	—	2.3	3.5	Ω	$I_{D} = -100 \text{ mA}$ $V_{GS} = -4 \text{ V}^{*1}$
Static drain to source on state resistance	$R_{\text{DS(on)}}^{}2$	—	5.0	9.0	Ω	$I_{\rm D} = -40 \text{ mA}$ $V_{\rm GS} = -2.5 \text{ V}^{*1}$
Foward transfer admittance	y <sub>fs</sub>	0.13	0.23	_	S	I <sub>D</sub> = -100 mA*1 V <sub>DS</sub> = -10 V
Input capacitance	Ciss	_	2.4	_	pF	$V_{\rm DS} = -10 \ V$
Output capacitance	Coss	_	31	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	0.6		pF	f = 1 MHz
Turn-on delay time	t <sub>d(on)</sub>	—	0.17	_	μs	$V_{GS} = -10 \text{ V}, \text{ I}_{D} = -0.1 \text{ A}$
Rise time	t,	_	0.68	_	μs	$R_{L} = 100 \Omega$
Turn-off delay time	t <sub>d(off)</sub>	_	3.0	_	μs	
Fall time	t <sub>f</sub>	_	2.8	_	μs	

Note: 1. Pulse Test

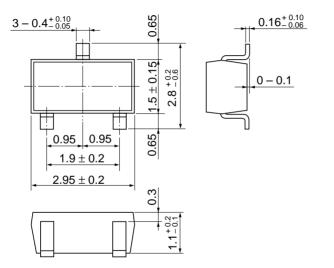








Unit: mm



Hitachi Code	MPAK
JEDEC	
EIAJ	Conforms
Weight (reference value)	0.011 g

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